

## 5.2A, 40V N-CHANNEL ENHANCEMENT MODE TRENCH POWER MOSFET

#### DESCRIPTION

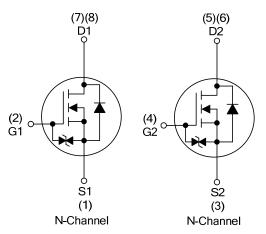
The UTC **UD8N04Z** is a N-channel enhancement mode power MOSFET using UTC's advanced technology to provide customers with an extremely low on-state resistance and superior switching performance.

The UTC **UD8N04Z** is suitable for high frequency DC-DC converters with synchronous rectification applications.

#### FEATURES

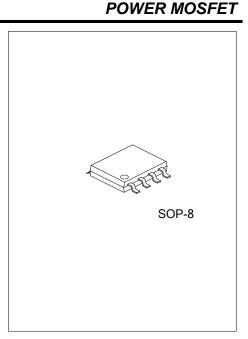
- \*  $R_{DS(ON)} \le 85 \text{ m}\Omega @ V_{GS}=10V, I_D=5.2A$
- $R_{DS(ON)} \le 112 \text{ m}\Omega @ V_{GS}=4.5V, I_{D}=4.0A$
- \* High Power and Current Handling Capability
- \* High Cell Density Trench Technology

#### SYMBOL

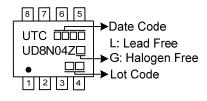


#### ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment						Decking			
Lead Free	Halogen Free	Package	1	2	З	4	5	6	7	8	Packing	
UD8N04ZL-S08-R	UD8N04ZG-S08-R	SOP-8	S1	G1	S2	G2	D2	D2	D1	D1	Tape Reel	
Note: Pin Assignment: G: Gate D: Drain S: Source												
UD8N04Z <u>G-SC</u>	(1) R: (2) S( e (3) G:	)8: S	OP-8	8	e an	d Le	ad F	ree,	L: L	ead Free		



### MARKING





#### ■ ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V <sub>DSS</sub>	40	V
Gate-Source Voltage		V <sub>GSS</sub>	±12	V
Continuous Drain Current	Continuous	Ι <sub>D</sub>	5.2	Α
Pulsed Drain Current (Note 2)	Pulsed	I <sub>DM</sub>	8	А
Power Dissipation (Note 3)		PD	1.47	W
Junction Temperature		TJ	+150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. Mounted on a ceramic board.

#### THERMAL CHARACTERISTICS

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ <sub>JA</sub>	85	°C/W

Note: Mounted on a ceramic board.

#### ■ ELECTRICAL CHARACTERISTICS (T<sub>A</sub> =25°C, unless otherwise specified)

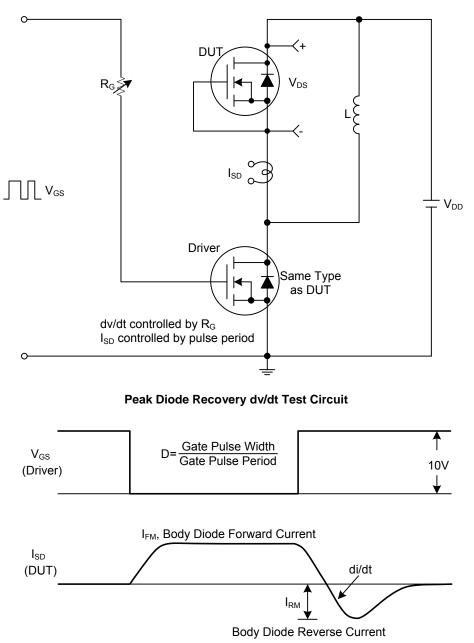
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS			·					
Drain-Source Breakdown Voltage	<b>BV</b> <sub>DSS</sub>	I <sub>D</sub> =250μΑ, V <sub>GS</sub> =0V	40			V		
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1	μA		
Cata Source Lookage Current	Forward	I <sub>GSS</sub>	V <sub>GS</sub> =+12V, V <sub>DS</sub> =0V			+10	μA	
Gate-Source Leakage Current	Reverse		V <sub>GS</sub> =-12V, V <sub>DS</sub> =0V			-10	μA	
ON CHARACTERISTICS								
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =1mA	1.0		3.0	V		
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.2A			85	mΩ	
			V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.0A			112	mΩ	
DYNAMIC PARAMETERS								
Input Capacitance		CISS			370		рF	
Output Capacitance		Coss	V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1.0MHz		69		рF	
Reverse Transfer Capacitance	C <sub>RSS</sub>			48		рF		
SWITCHING PARAMETERS								
Total Gate Charge (Note 1)		$Q_{G}$	V <sub>DS</sub> =20V, V <sub>GS</sub> =5.0V, I <sub>D</sub> =4.0A,		5.3		nC	
Gate to Source Charge		Q <sub>GS</sub>	$V_{DS}=20V$ , $V_{GS}=5.0V$ , $V_{D}=4.0A$ , $I_{G}=1mA$ (Note 1, 2)		2.1		nC	
Gate to Drain Charge		$Q_{GD}$			0.8		nC	
Turn-on Delay Time (Note 1)		t <sub>D(ON)</sub>			6.6		ns	
Rise Time		t <sub>R</sub>	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A,		14		ns	
Turn-off Delay Time		t <sub>D(OFF)</sub>	R <sub>G</sub> =10Ω (Note 1, 2)		33		ns	
Fall-Time		t <sub>F</sub>			24		ns	
SOURCE- DRAIN DIODE RATINGS	AND CHA	RACTERIS	ГІСЅ					
Maximum Body-Diode Continuous Current		ls				1.6	А	
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				8	А	
Drain-Source Diode Forward Voltage (Note 1)		V <sub>SD</sub>	I <sub>S</sub> =4.0A, V <sub>GS</sub> =0V			1.2	V	

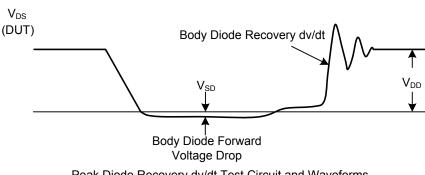
Notes: 1. Pulse Test: Pulse width  $\leq$  10µs, Duty cycle  $\leq$  1%.

2. Essentially independent of operating temperature.



#### TEST CIRCUITS AND WAVEFORMS



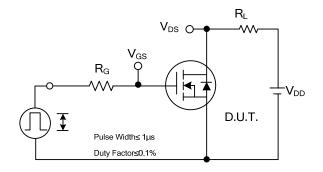


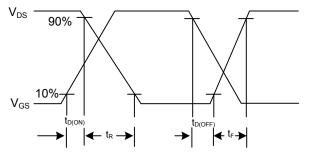
Peak Diode Recovery dv/dt Test Circuit and Waveforms

#### Peak Diode Recovery dv/dt Waveforms



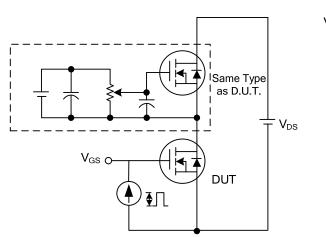
#### TEST CIRCUITS AND WAVEFORMS



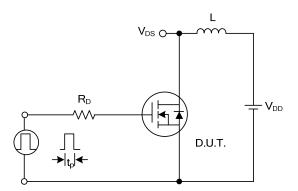


**Switching Waveforms** 

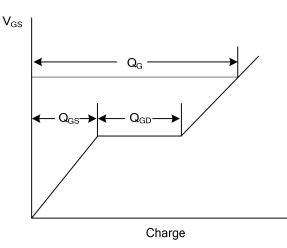




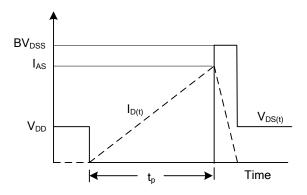
Gate Charge Test Circuit



Unclamped Inductive Switching Test Circuit



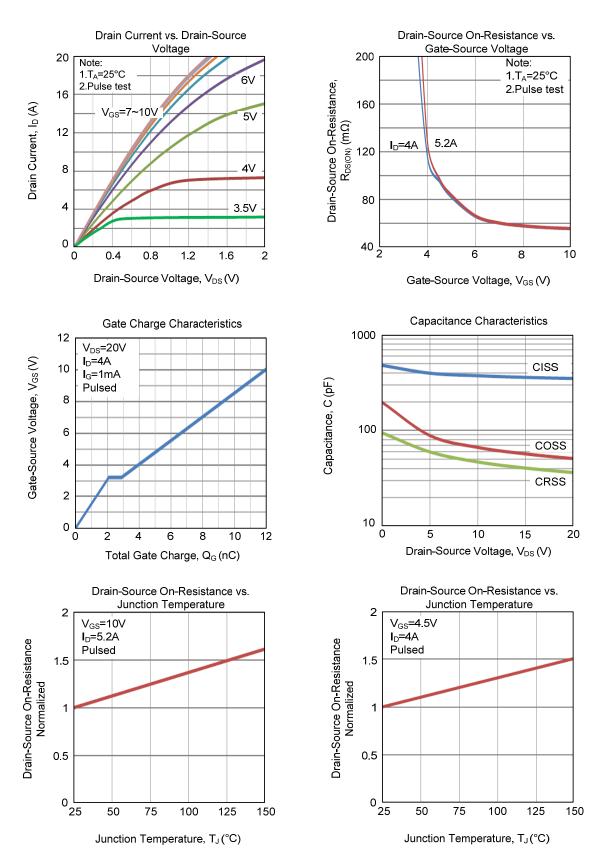




**Unclamped Inductive Switching Waveforms** 

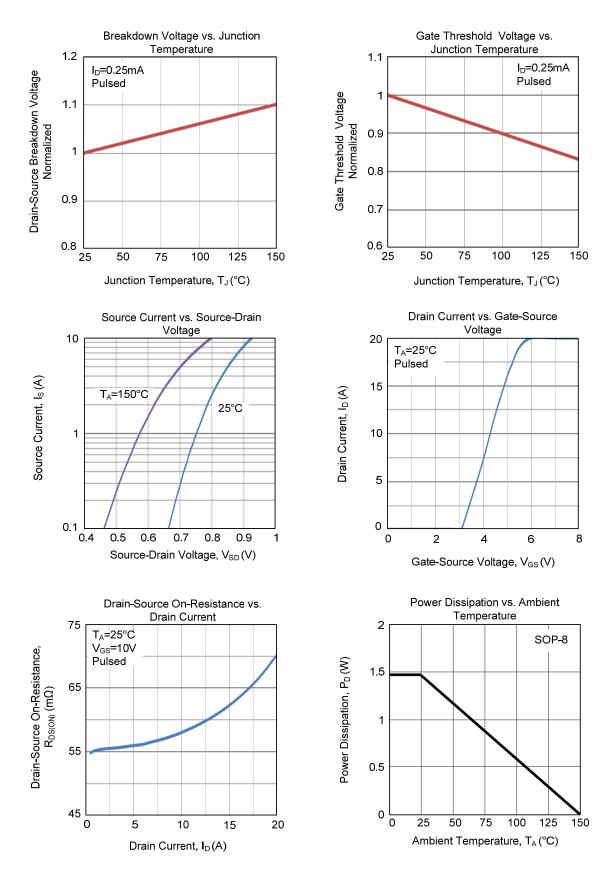


### TYPICAL CHARACTERISTICS



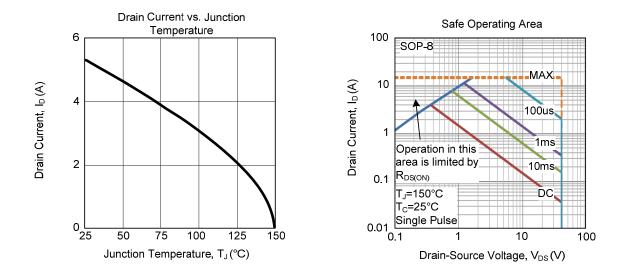


### TYPICAL CHARACTERISTICS (Cont.)





### TYPICAL CHARACTERISTICS (Cont.)



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